

CBR02C808B9GAC

CBR-SMD RF COG, Ceramic, 0.8 pF, +/-0.1 pF, 6.3 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201 / 0603



Click [here](#) for the 3D model.

General Information

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|--------------------------|--|
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| Typical Component Weight | 0.3 mg |
| Notes | Solder Reflow Only. |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

| | |
|----------------------|------------------|
| L | 0.6mm +/-0.03mm |
| W | 0.3mm +/-0.03mm |
| T | 0.3mm +/-0.03mm |
| B | 0.15mm +/-0.05mm |
| Case Code (EIA / mm) | 0201 / 0603 |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 15000 |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 0.8 pF |
| Tolerance | +/-0.1 pF |
| Voltage DC | 6.3 VDC |
| Dielectric Withstanding Voltage | 15.75 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Dissipation Factor | 0.24% |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 10 GOhms |
| Quality Factor | 416 |

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